

Substrate Road map ①

プリプレグベーステクノロジー（サブトラ工法）石巻工場

項目		FY2026		FY2027		FY2028	
		HVM	Proto Type	HVM	Proto Type	HVM	Proto Type
L/S	Subtractive	40/40	35/35	40/40	35/35	40/40	35/35
Thickness (Core)		60	50	60	50	60	50
Thickness (Prepreg)		30 (#1027)	25 (#1017)	25 (#1017)	20 (#1010)	25 (#1017)	20 (#1010)
LVH/Land Dia. (Laser)		Φ75/Φ150 (PP<40)	Φ60/Φ125 (PP<30)	Φ75/Φ150 (PP<40)	Φ60/Φ125 (PP<30)	Φ75/Φ150 (PP<40)	Φ60/Φ125 (PP<30)
BVH/Land Dia. (Drill)		Φ105/Φ200	Φ105/Φ200	Φ105/Φ200	Φ105/Φ200	Φ105/Φ200	Φ105/Φ200
TH/Land Dia. (Drill)		Φ200/Φ450	Φ200/Φ400 (APR<6.4)	Φ200/Φ450	Φ200/Φ400 (APR<6.4)	Φ200/Φ450	Φ200/Φ400 (APR<6.4)
Layer		14L (MLB, HDI)	16L (MLB, HDI)	14L (MLB, HDI)	TBD	TBD	TBD
Surface Treatment (OutSource)		OSP、電解Ni/Au、無電解Ni/厚付けAu、無電解Ni/Pd/Au					

ABFベーステクノロジー（SAP工法）石巻工場

項目			FY2026		FY2027		FY2028	
			HVM	Proto Type	HVM	Proto Type	HVM	Proto Type
Max Build-up Layer Count			9	10	10	12	12	12
Max Via Stack			6	10	10	12	12	12
Trace	BU L/S (SAP)		8/8	7/7	7/7	6/6	6/6	5/5
	BU Trace Thickness		12	10	10	8	8	6
	Core L/S (Subtractive)		45/45	45/45	45/45	40/40	40/40	35/35
Via/Land	BU	Via	Φ50	Φ50	Φ50	Φ45	Φ45	Φ40
		Land	Φ80	Φ75	Φ75	Φ70	Φ70	Φ70
TH/Land Dia. (Drill)	Core Thickness	0.4mm	Φ105/Φ200	Φ105/Φ200	Φ105/Φ200	Φ105/Φ200	Φ105/Φ200	Φ105/Φ200
		0.8mm	Φ150/Φ250	Φ105/Φ200	Φ105/Φ200	Φ105/Φ200	Φ105/Φ200	Φ105/Φ200
		1.2mm	Φ150/Φ250	Φ150/Φ250	Φ150/Φ250	Φ150/Φ250	Φ150/Φ250	Φ150/Φ250
		1.4mm	Φ200/Φ300	Φ200/Φ300	Φ200/Φ300	Φ200/Φ300	Φ200/Φ300	Φ200/Φ300
SR	Opening (μm)		Φ65	Φ60	Φ60	Φ55	Φ55	Φ50
	Cu Pad (μm)		Φ90	Φ85	Φ85	Φ80	Φ80	Φ75
SOP	Min Bump Pitch (μm)		120	110	110	100	100	90
Material	Core		E-700G (R) E705G	HUL832RS (LCA) HIL832NSA (TLC) E-795G R-1515V	E-700G (R) E705G E-795G R-1515V HUL832RS (LCA) HIL832NSA (TLC)	TBD	E-700G (R) E705G E-795G R-1515V HUL832RS (LCA) HIL832NSA (TLC)	TBD
	BU Film		GX92 GXT31 GL102F	GL107 NX04H NQ07XP	GX92 GXT31 GL102F GL107 NX04H NQ07XP	TBD	GX92 GXT31 GL102F GL107 NX04H NQ07XP	TBD
	SR	Liquid	SR7300G SR7400A	TBD	SR7300G SR7400A	TBD	SR7300G SR7400A	TBD
		Film	—	SR-FA SR-FK	SR-FA SR-FK	TBD	SR-FA SR-FK	TBD